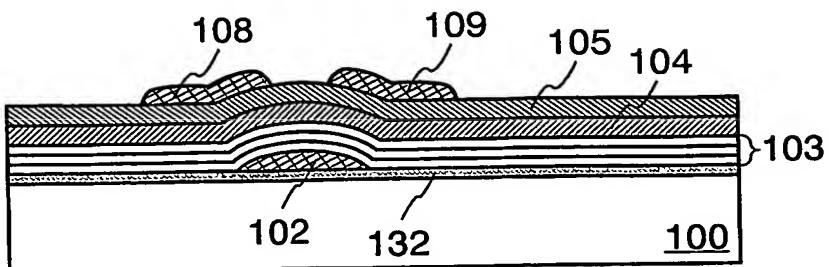
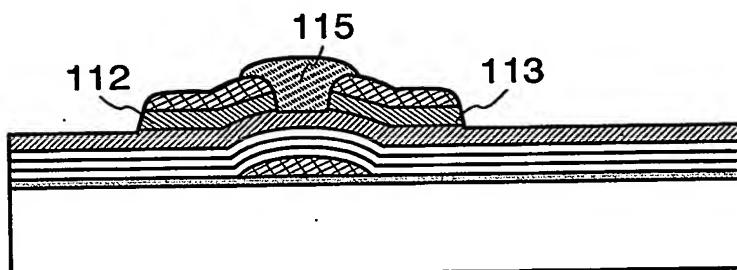
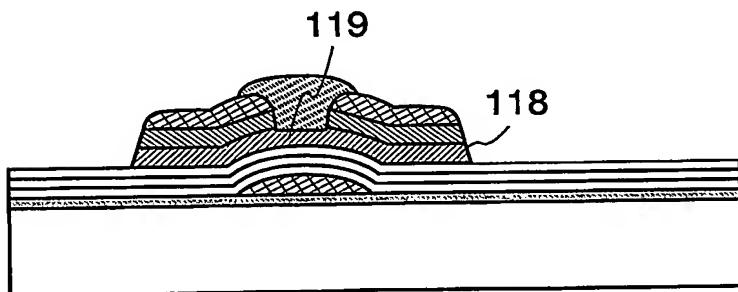
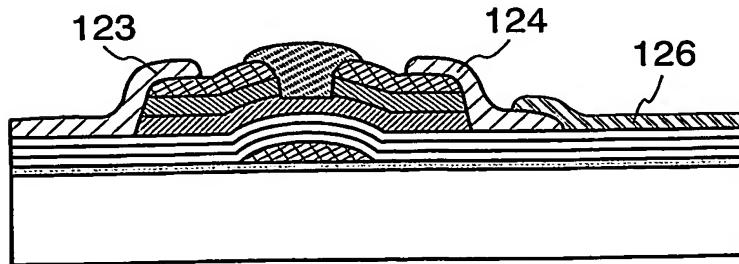


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FIG. 1A**FIG. 1B****FIG. 1C****FIG. 1D**

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FIG. 2A

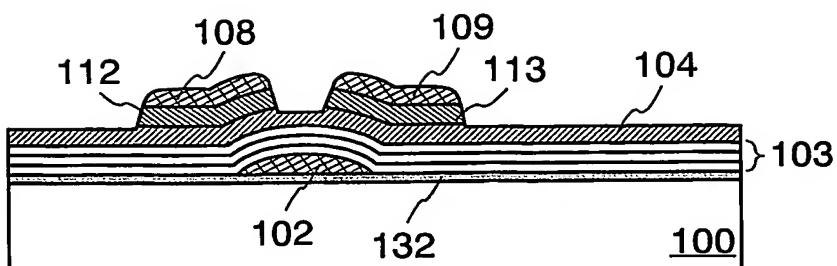


FIG. 2B

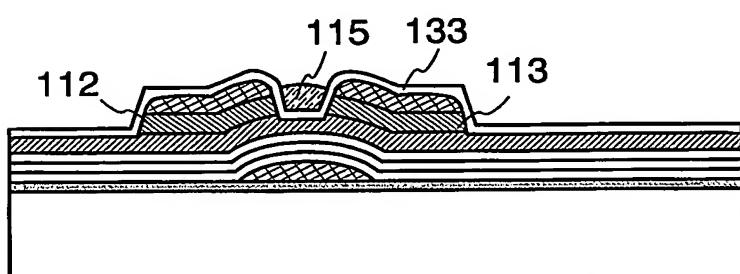


FIG. 2C

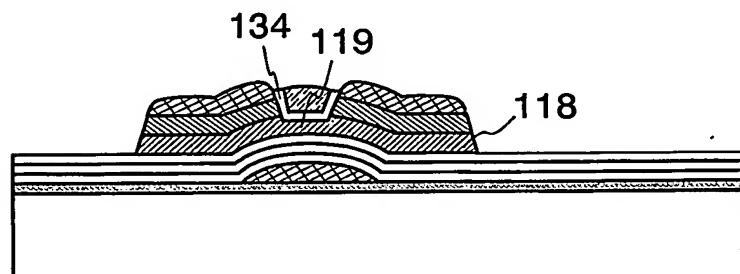
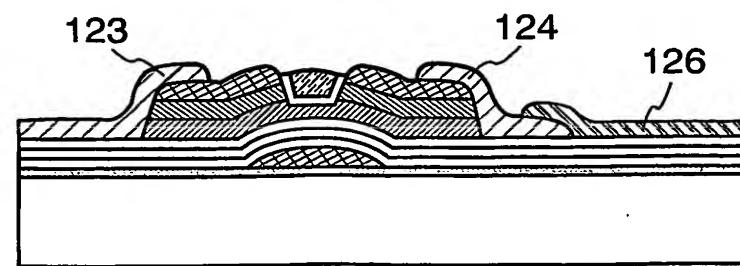


FIG. 2D



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FIG. 3A

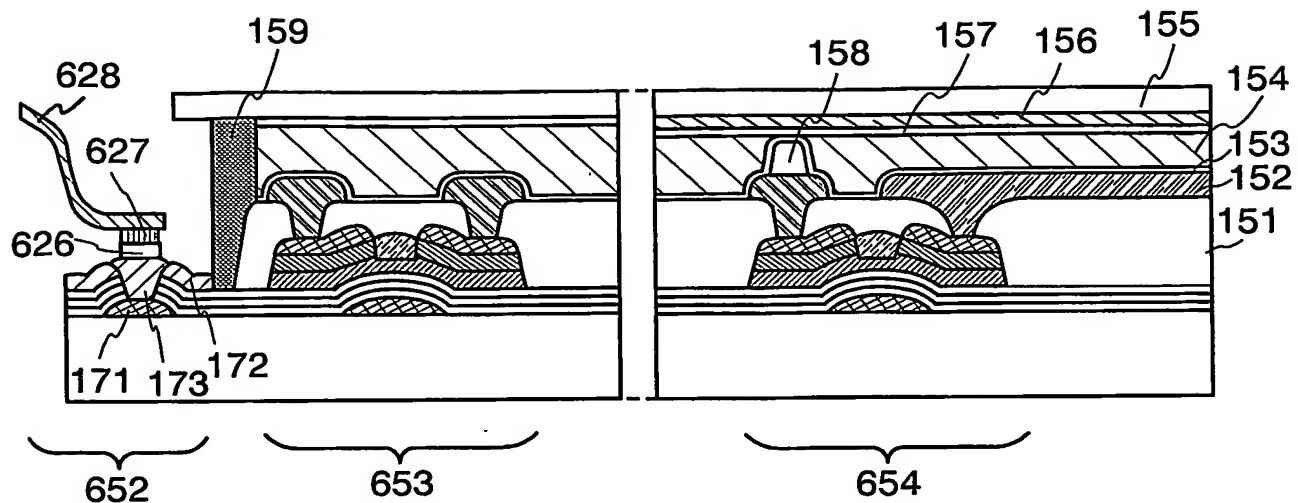


FIG. 3B

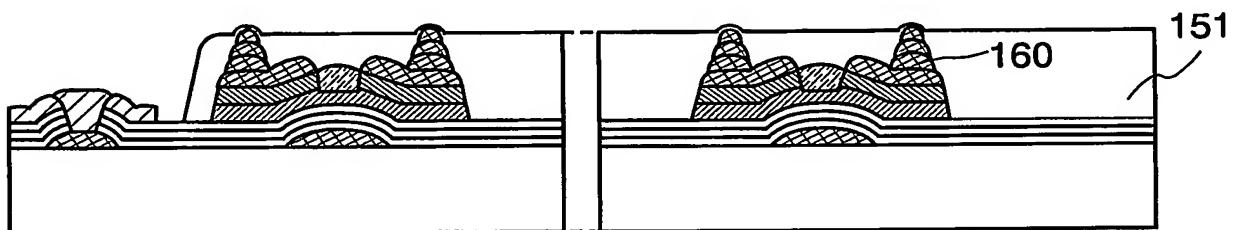
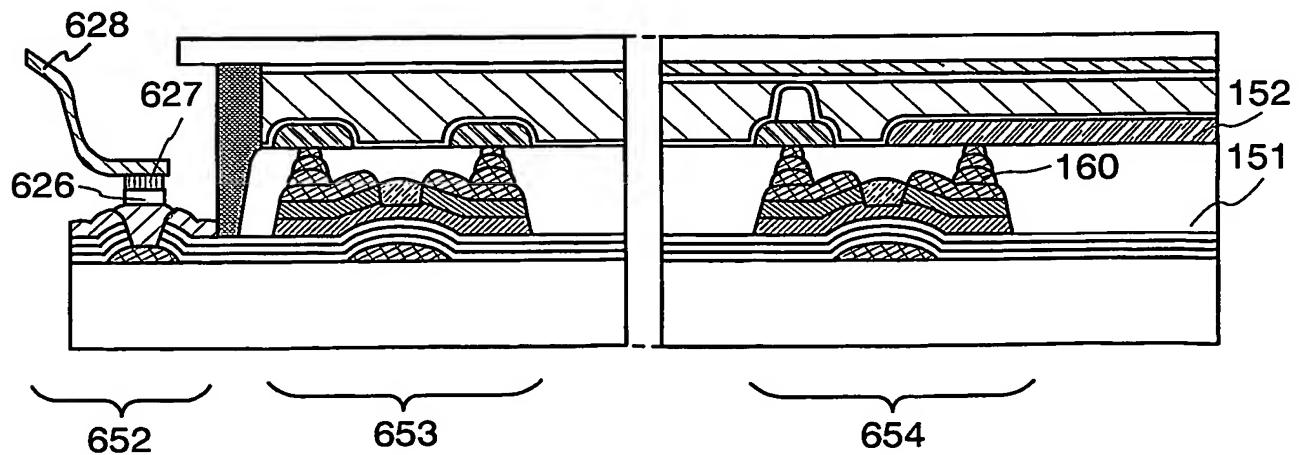


FIG. 3C



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FIG. 4A

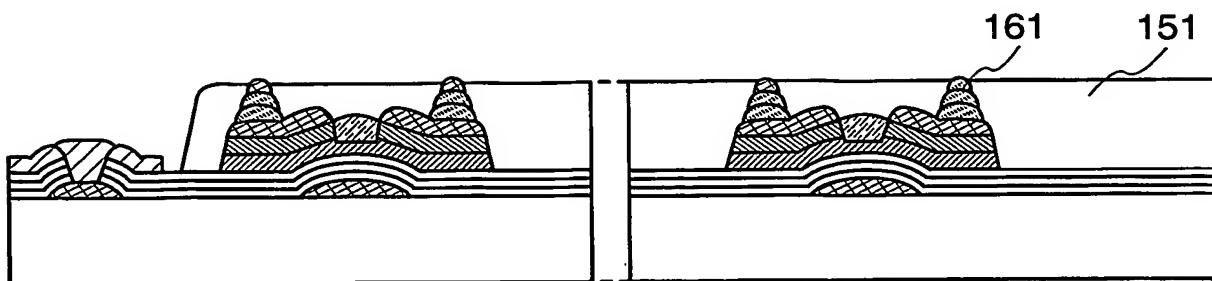
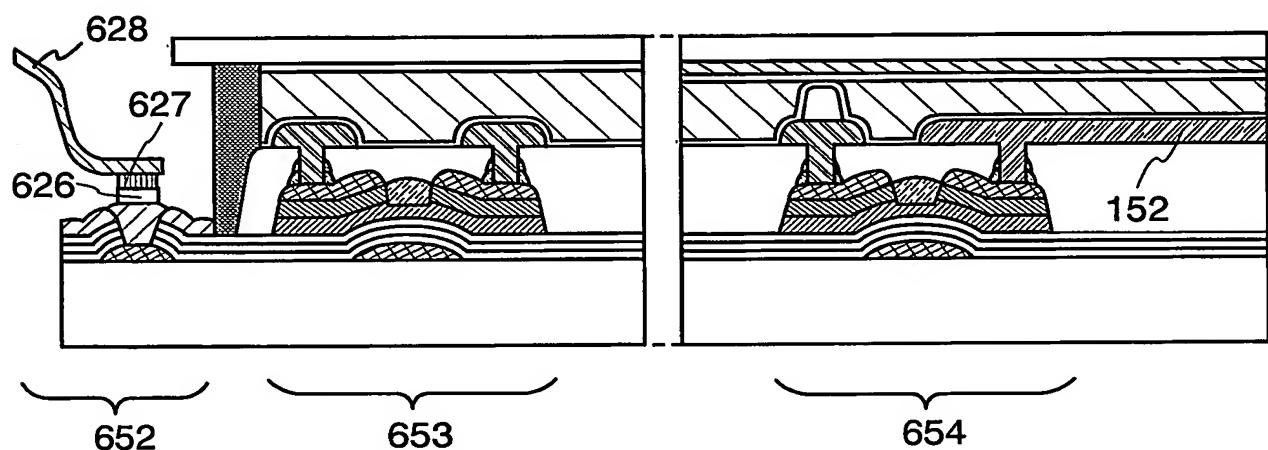


FIG. 4B



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FIG. 5A

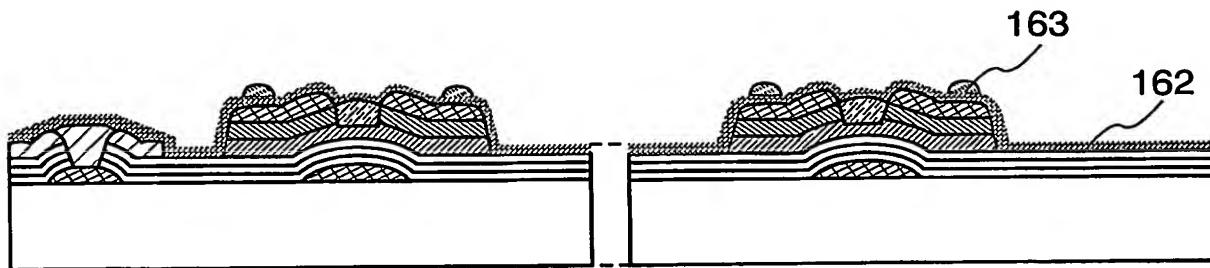


FIG. 5B

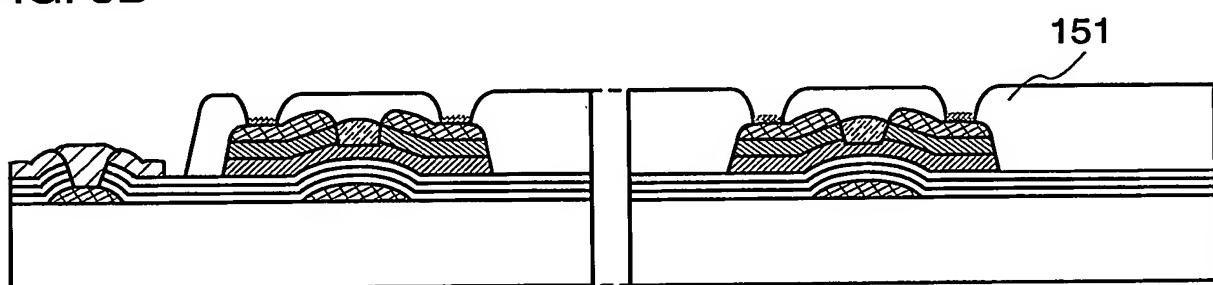
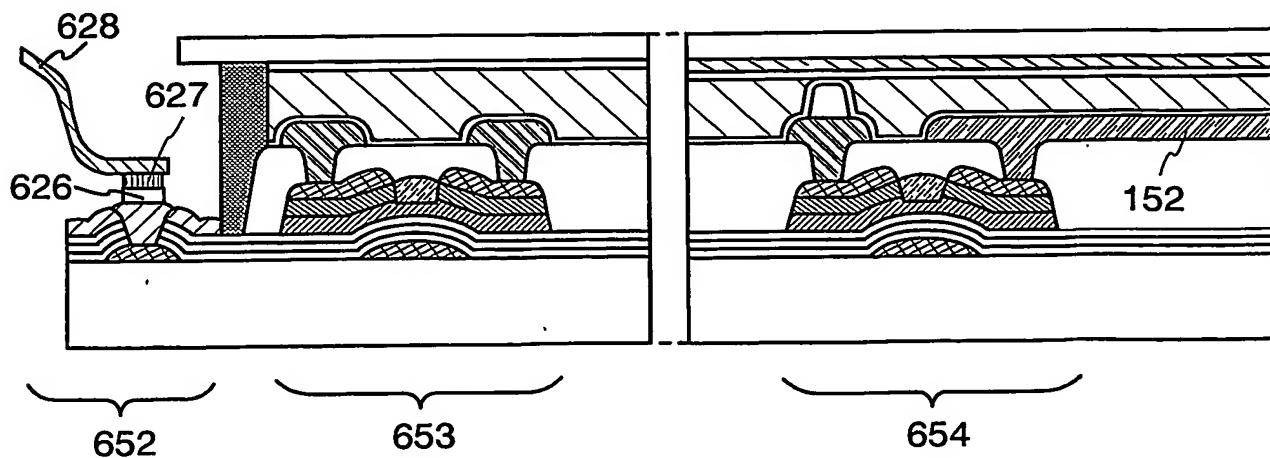


FIG. 5C



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FIG. 6A

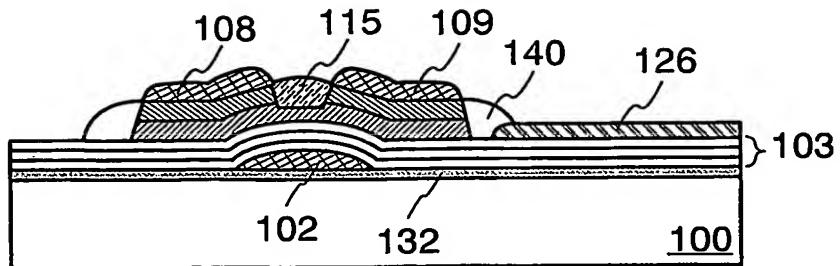


FIG. 6B

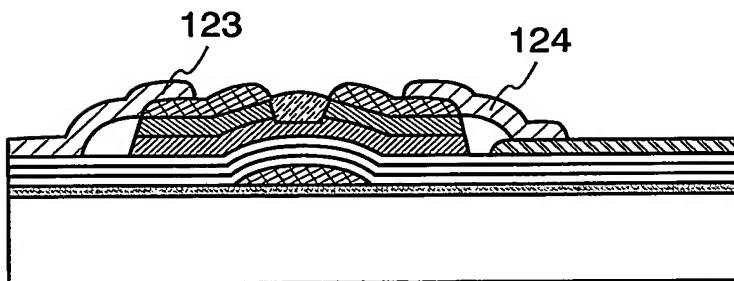
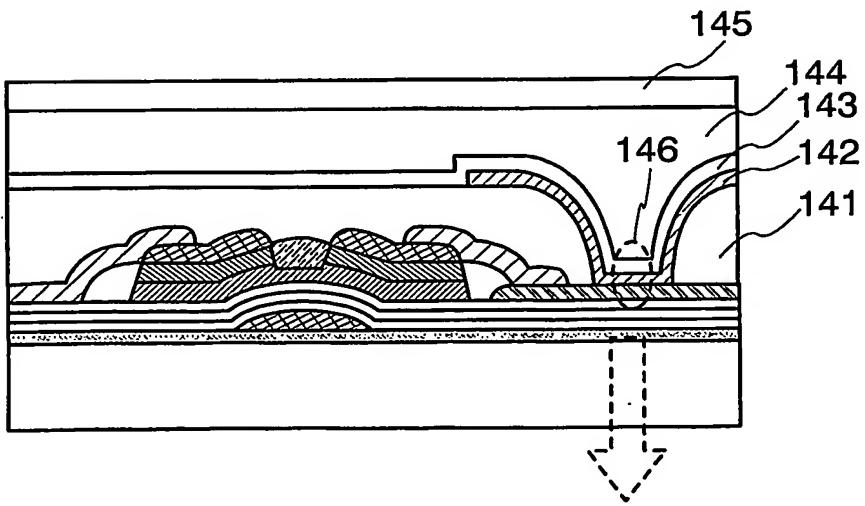


FIG. 6C



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FIG. 7A

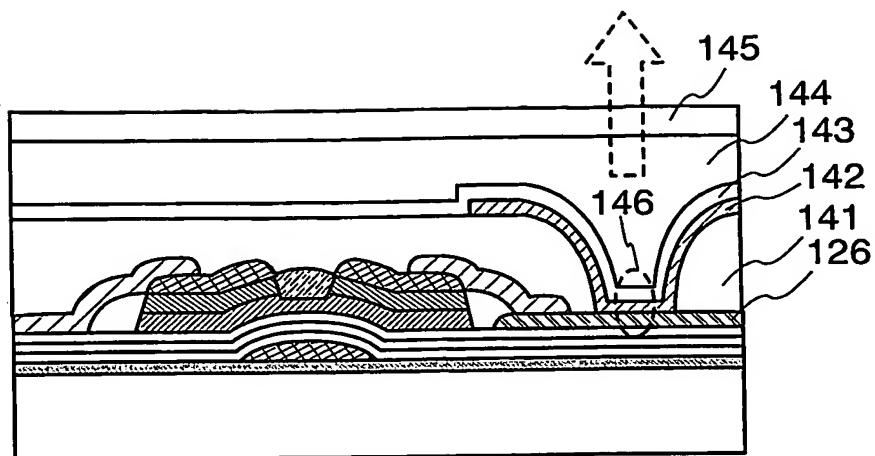


FIG. 7B

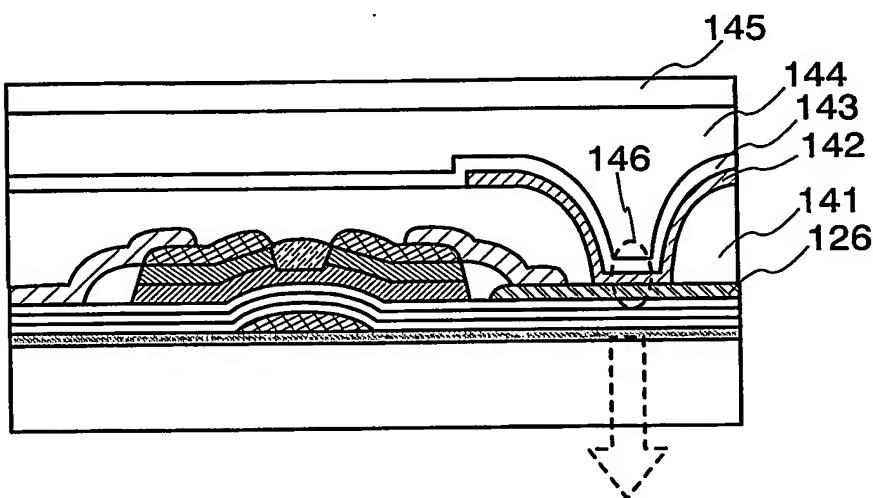
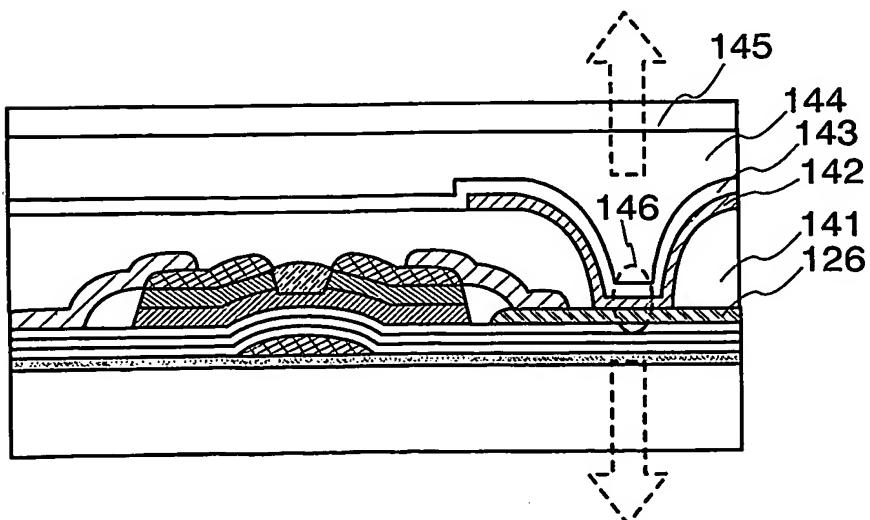
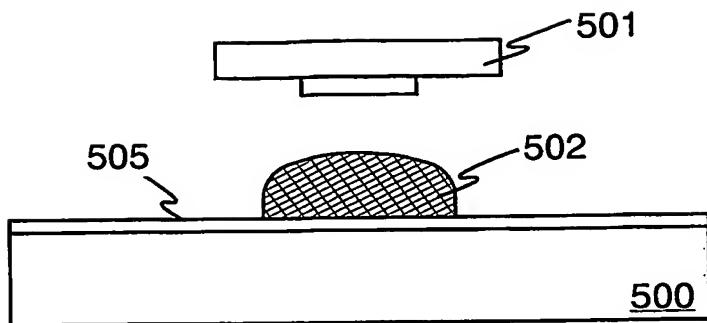


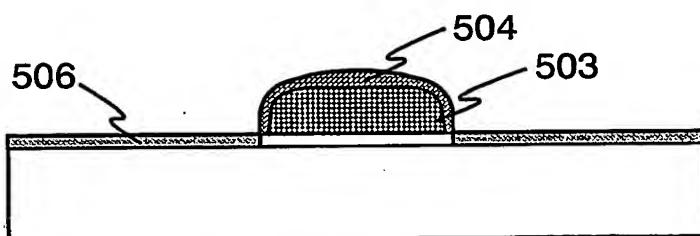
FIG. 7C



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FIG. 8A

DRYING OR BAKING

FIG. 8B

BAKING UNDER
ATMOSPHERE
CONTAINING
OXYGEN OR OXYGEN
PLASMA TREATMENT

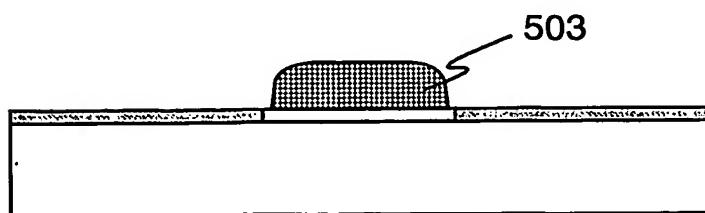
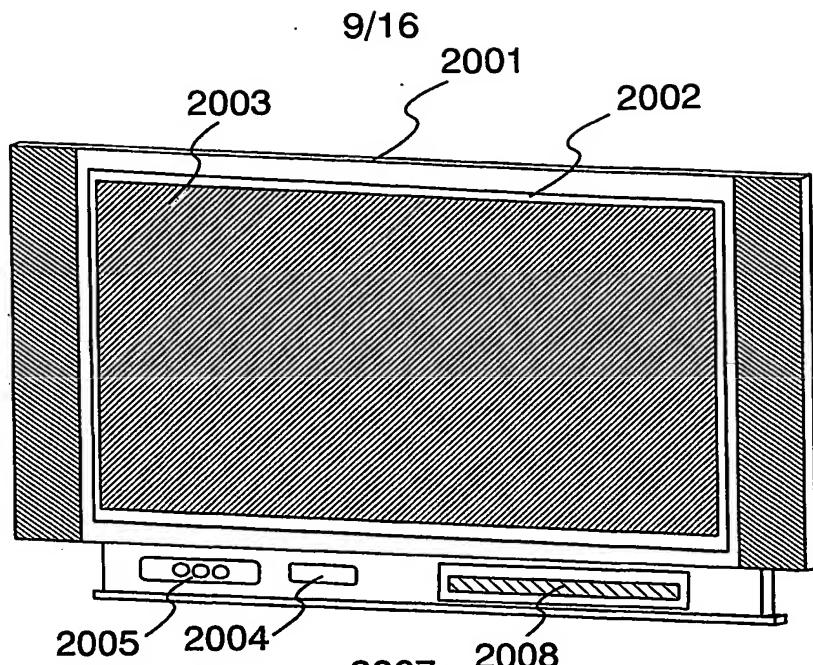
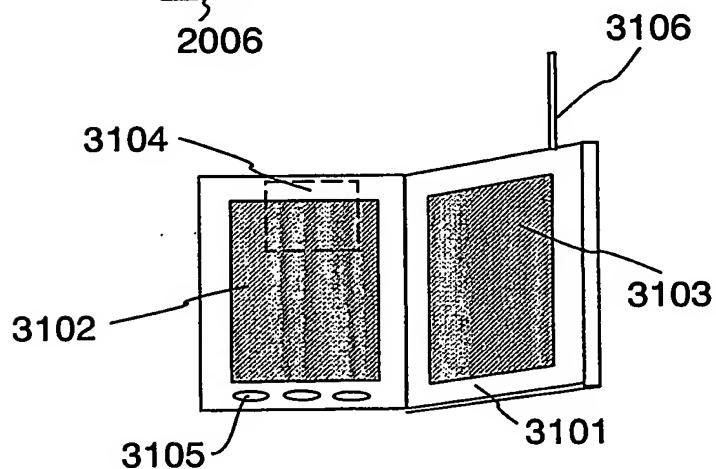
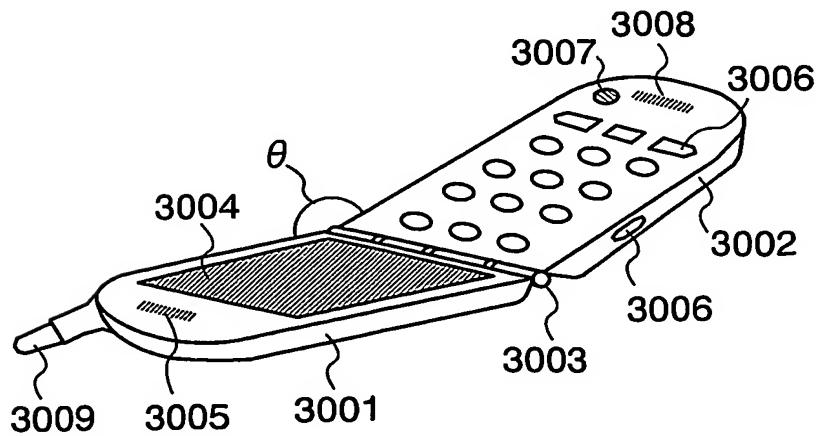
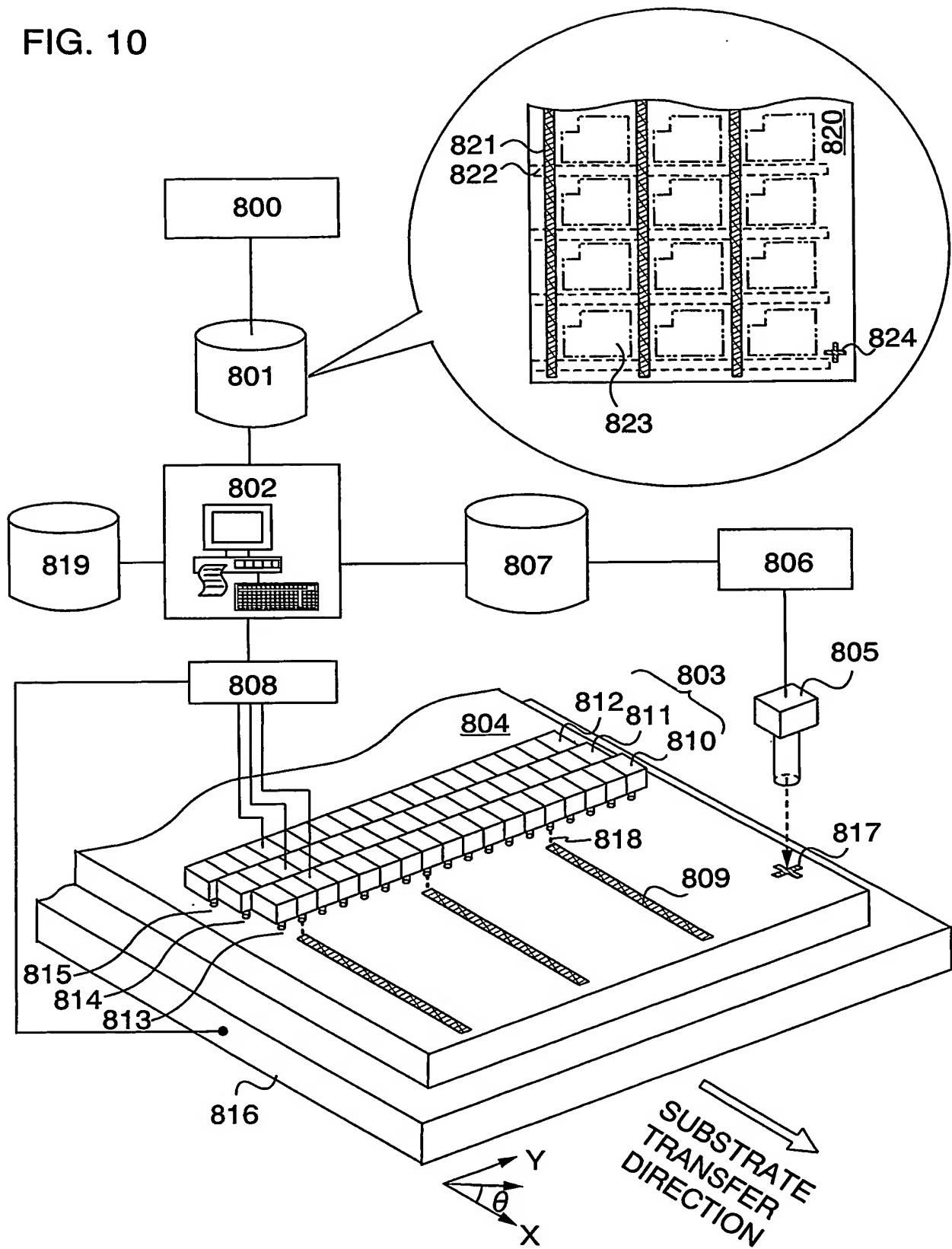
FIG. 8C

FIG. 9A**FIG. 9B****FIG. 9C**

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FIG. 10



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FIG. 11A

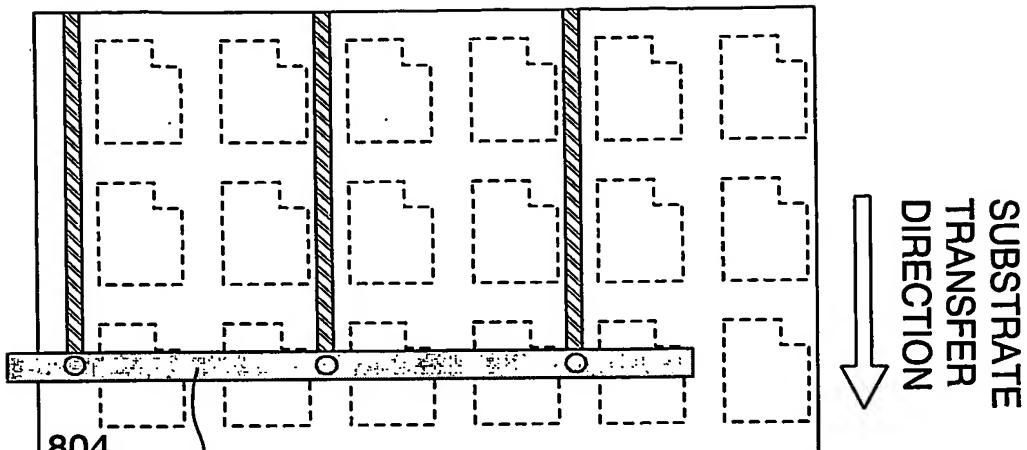


FIG. 11B

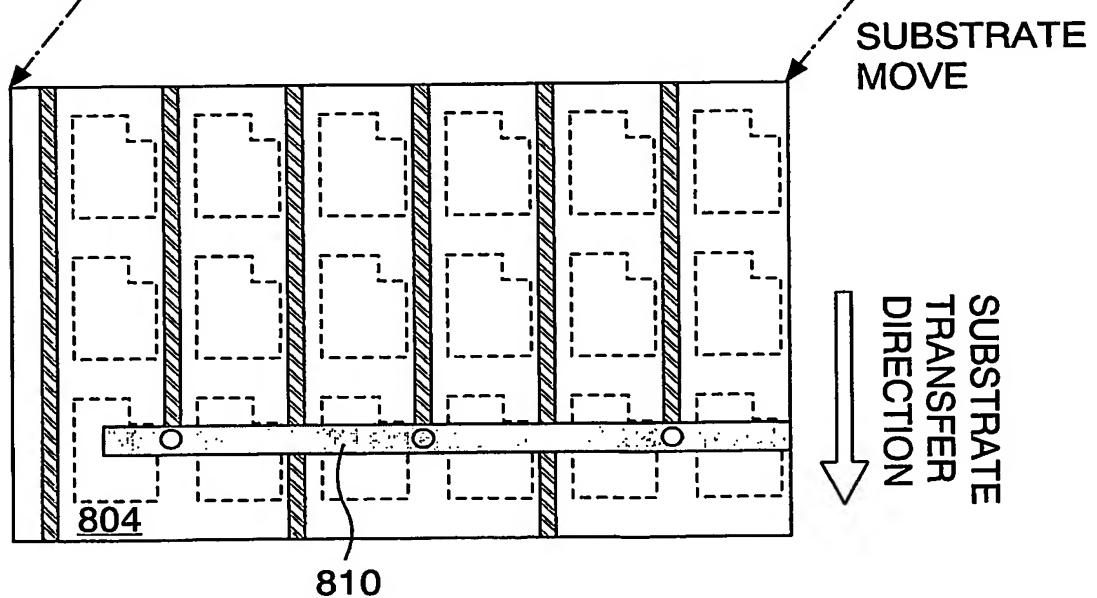


FIG. 12A

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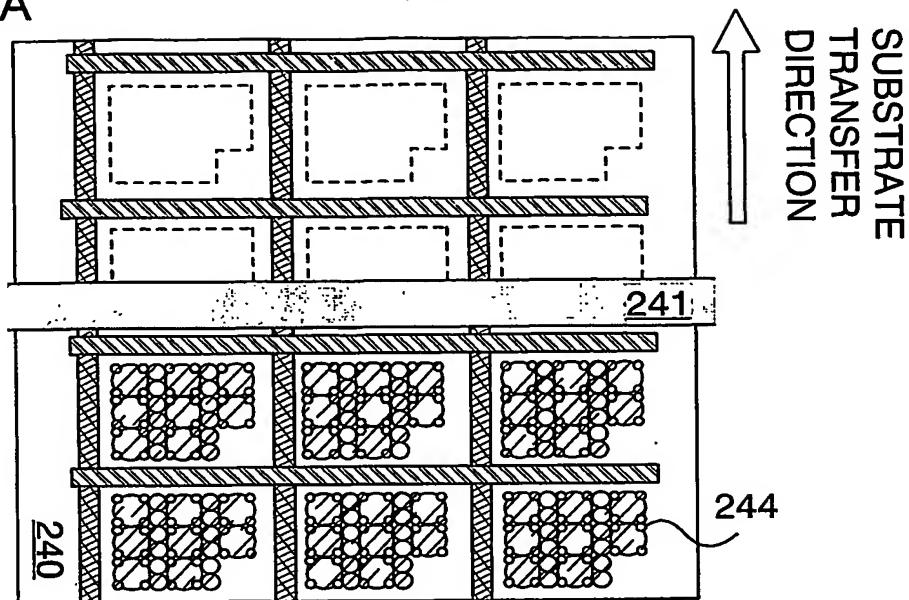
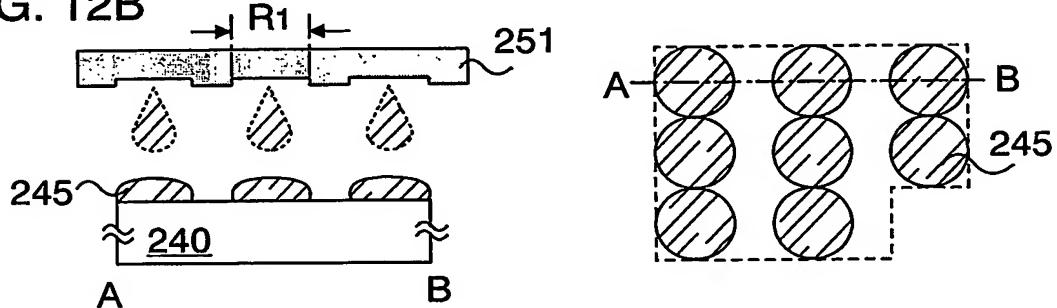
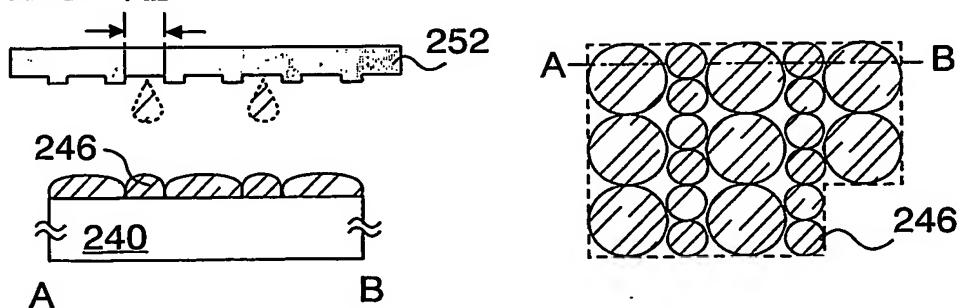
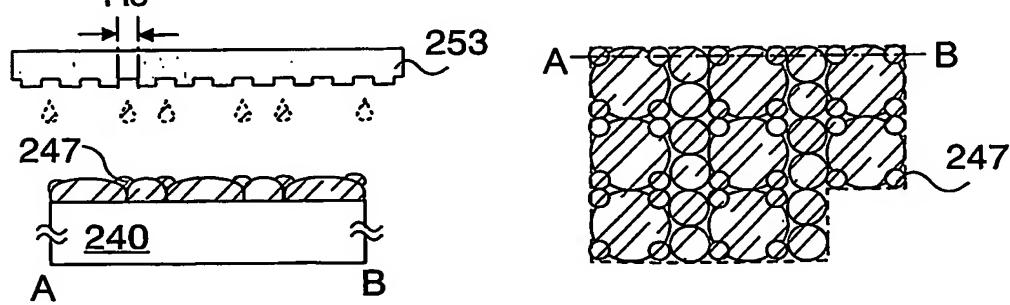
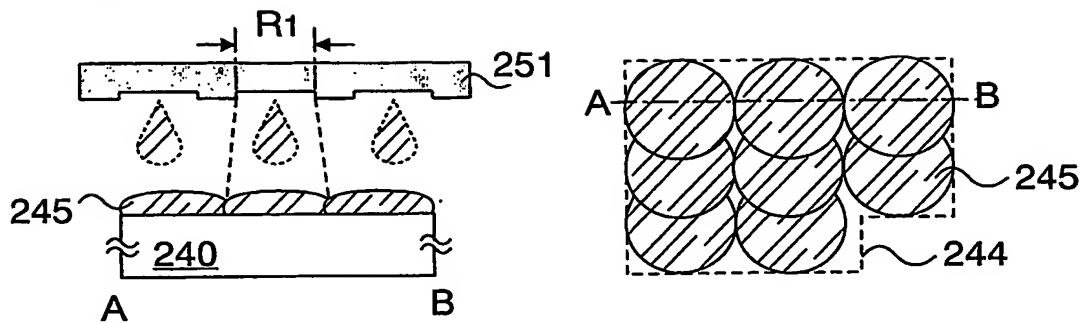
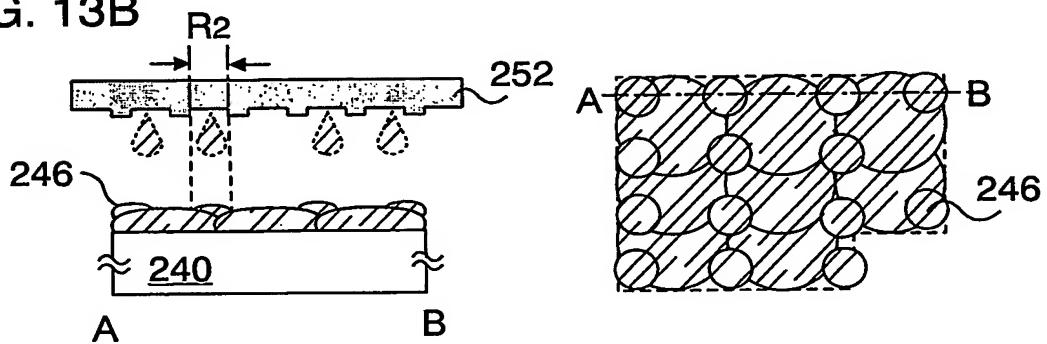
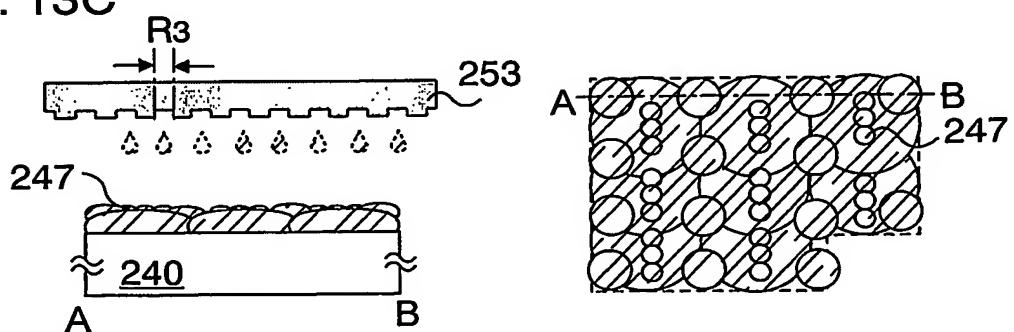


FIG. 12B

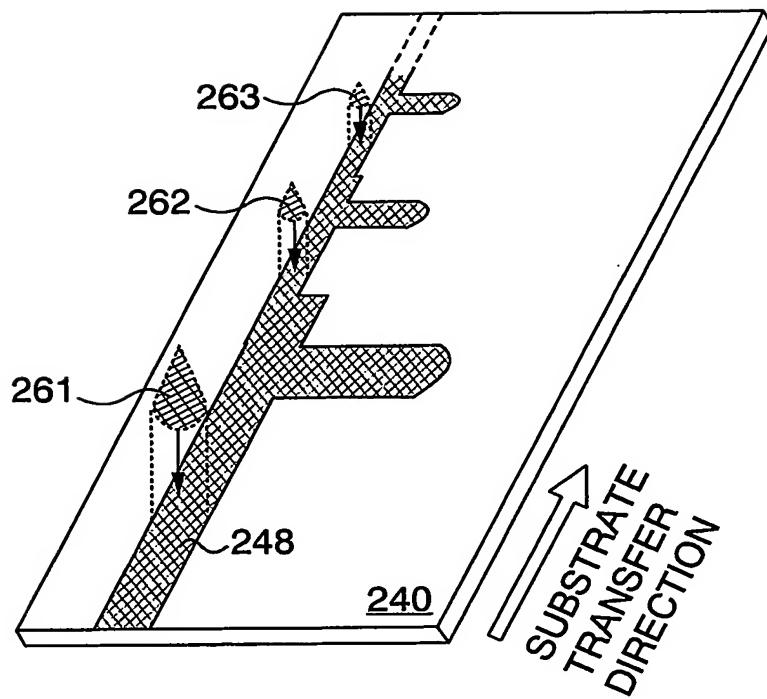
FIG. 12C R₂FIG. 12D R₃

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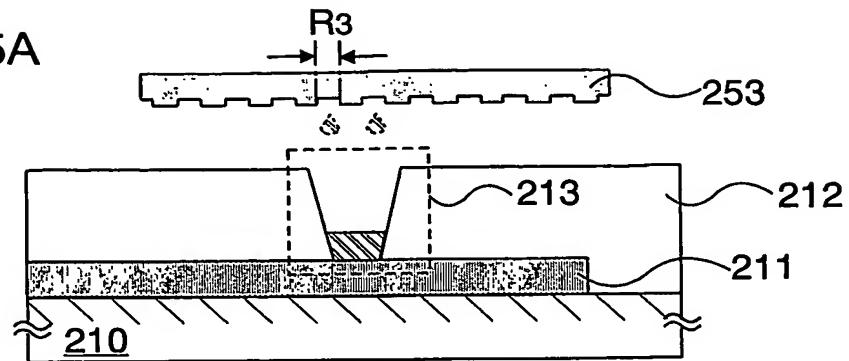
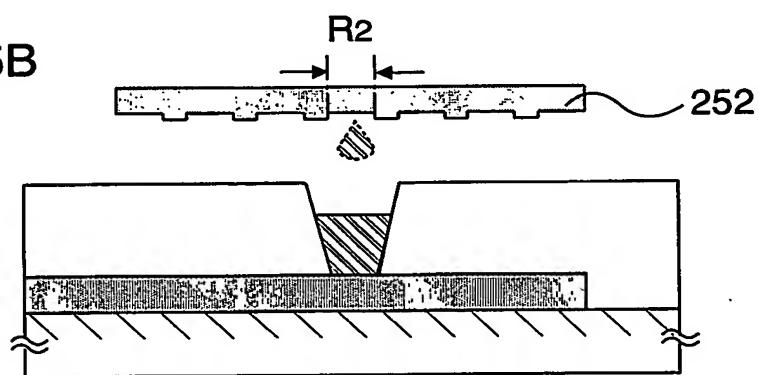
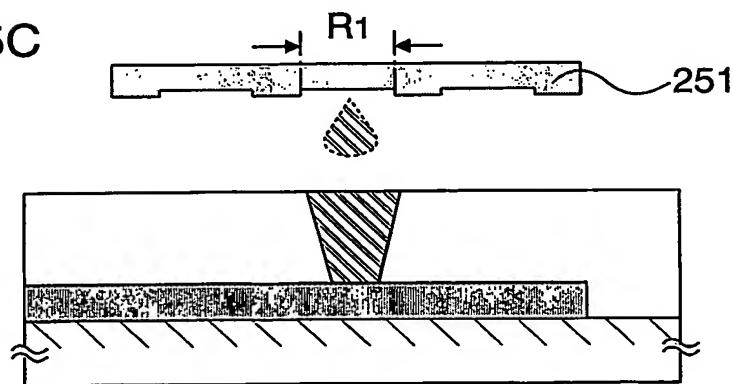
FIG. 13A**FIG. 13B****FIG. 13C**

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FIG. 14



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FIG. 15A**FIG. 15B****FIG. 15C**

[EXPLANATION OF REFERENCES]

100: Substrate, 102: Gate electrode layer, 103: Gate insulating film, 104: Semiconductor film, 105: N-type semiconductor film, 108: Source electrode, 109: Drain electrode, 112: Source region, 113: Drain region, 115: Insulating film, 118: Island-like semiconductor region, 119: Channel region, 123: Source wiring, 126: Pixel electrode, 132: Titanium oxide film, 134: Insulating film, 140: Insulator, 141: Bank, 142: Organic compound layer, 143: Electron injecting electrode, 144: Passivation film, 145: Opposing substrate, 146: Light-emitting element, 151: Planarization film, 152: Drain wiring, 153: Orientation film, 154: Liquid crystal layer, 155: Opposing substrate, 156: Transparent conductive film, 157: Orientation film, 158: Column-like spacer, 159: Sealant, 160: Column-like conductor, 161: Pillar insulator, 162: Liquid-shedding material, 163: Mask, 171: Wiring, 172: Conductor, 173: Conductor, 500: Glass substrate, 501: Nozzle, 502: Nano paste, 503: Conductor containing metal chains, 504: Film formed by organic ingredients, 626: Terminal electrode, 627: Anisotropic conductive film, 628: FPC, 652: Terminal portion, 654: Pixel TFT, 800: Circuit design tool, 801: Data of thin film pattern, 802: Computer, 805: Imaging means, 806: Image processing device, 807: Position information of alignment marker, 808: Controller, 816: XYθ stage, 817: Alignment marker, 819: Database, 2001: Housing, 2002: Display module, 2003: Main-screen, 2004: Modem, 2005: Receiver, 2006: Wireless remote control, 2007: Display portion, 2008: Sub-screen, 3001: Display panel, 3002: Operation panel, 3003: Connecting portion, 3004: Display portion, 3005: Voice output portion, 3006: Operation key, 3007: Power source switch, 3008: Voice input portion, 3009: Antenna, 3101: Main body, 3102: Display portion, 3103: Display portion, 3104: Memory medium, 3105: Operation switch, 3106: Antenna